

U.S.S.N. 10,791,247

Claim Amendments

Please amend claims 1, 13, 15, 17, and 23 as follows:

U.S.S.N. 10,791,247

Listing of Claims

1. (currently amended) A method of cleaning substrates,
comprising the steps of:

providing a cleaning fluid;

mixing a solvent with said cleaning fluid to form a
~~non-supercritical~~ cleaning fluid mixture in a non-supercritical
state;

delivering said ~~non-supercritical~~ cleaning fluid
mixture in said non-supercritical state to a cleaning chamber;

forming a supercritical cleaning fluid from said ~~non-~~
~~supercritical~~ cleaning fluid mixture in said non-supercritical
state in said cleaning chamber; and

contacting the substrate with said supercritical
cleaning fluid in said cleaning chamber.

2. (original) The method of claim 1 wherein said cleaning fluid
is carbon dioxide.

U.S.S.N. 10,791,247

3. (previously presented) The method of claim 1 wherein said contacting the substrate with said supercritical cleaning fluid comprises the step of circulating the supercritical cleaning fluid within said cleaning chamber.

Claims 4-6 (canceled)

7. (original) The method of claim 1 wherein said supercritical cleaning fluid is non-conductive.

8. (original) The method of claim 1 wherein said cleaning fluid is selected from the group consisting of methane, ethane, propane, ammonia, nitric oxide, fluoromethane and difluoromethane.

9. (previously presented) The method of claim 1 wherein said solvent is an alcohol.

10. (original) The method of claim 1 wherein each of said substrates comprises exposed N-doped and P-doped regions.

11. (original) The method of claim 1 wherein each of said substrates comprises an exposed conductive layer.

U.S.S.N. 10,791,247

12. (original) The method of claim 11 wherein each of said substrates comprises exposed N-doped and P-doped regions and an exposed conductive layer.

13. (currently amended) A method of cleaning a substrate to reduce galvanic corrosion of a substrate comprising N-doped and P-doped regions and a conductive layer, comprising the steps of:

providing non-supercritical cleaning fluid cleaning solution;

mixing a solvent with said cleaning fluid to form a ~~non-supercritical~~ cleaning fluid mixture in a non-supercritical state;

delivering said ~~non-supercritical~~ cleaning fluid mixture in said non-supercritical state to a cleaning chamber;

forming a supercritical cleaning fluid mixture from said ~~non-supercritical~~ cleaning fluid mixture in said non-supercritical state in said cleaning chamber; and

contacting the substrate with said supercritical cleaning fluid mixture in said cleaning chamber.

U.S.S.N. 10,791,247

14. (canceled)

15. (currently amended) The method of claim 13 wherein said ~~non-supercritical~~ cleaning fluid comprises carbon dioxide.

16. (canceled)

17. (currently amended) A method of cleaning a substrate to reduce galvanic corrosion of exposed conductors, comprising the steps of:

providing said substrate comprising exposed metal lines;

providing a cleaning fluid selected from the group consisting of carbon dioxide, methane, ethane, propane, ammonia, nitric oxide, fluoromethane and difluoromethane;

mixing a solvent with said cleaning fluid to form a ~~non-supercritical~~ cleaning fluid mixture in a non-supercritical state;

delivering said ~~non-supercritical~~ cleaning fluid

U.S.S.N. 10,791,247

mixture in said non-supercritical state to a cleaning chamber;

forming a supercritical cleaning fluid from said ~~non-supercritical~~ cleaning fluid in said non-supercritical state in said cleaning chamber; and

contacting the substrate with said supercritical cleaning fluid.

18. (canceled)

19. (original) The method of claim 17 wherein said supercritical cleaning fluid is non-conductive.

20. (previously presented) The method of claim 17 wherein said substrate comprises exposed N-doped and P-doped regions.

21. (previously presented) The method of claim 1, wherein the solvent is selected from the group consisting of isopropyl alcohol or other alcohols, ethylene glycol, hydrogen fluoride and ammonium hydroxide.

22. (previously presented) The method of claim 1, wherein the substrate comprises exposed metal lines.

U.S.S.N. 10,791,247

23. (currently amended) The method of claim 13, wherein said ~~non-supercritical~~ cleaning fluid is selected from the group consisting of methane, ethane, propane, ammonia, nitric oxide, fluoromethane and difluoromethane.

24. (previously presented) The method of claim 17, wherein said solvent is selected from the group consisting of alcohols, ethylene glycol, hydrogen fluoride and ammonium hydroxide.

25. (previously presented) The method of claim 13 wherein said contacting the substrate with said supercritical cleaning fluid comprises the step of circulating the supercritical cleaning fluid within said cleaning chamber.

26. (previously presented) The method of claim 17 wherein said contacting the substrate with said supercritical cleaning fluid comprises the step of circulating the supercritical cleaning fluid within said cleaning chamber.